

# PATENT ASSIGNMENT

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT												
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT												
<b>CONVEYING PARTY DATA</b>													
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr> <td>Chi-Chang CHEN</td> <td>08/19/2010</td> </tr> <tr> <td>Huan-Ruei SHIU</td> <td>08/19/2010</td> </tr> <tr> <td>Chun-Hsing WU</td> <td>08/19/2010</td> </tr> <tr> <td>Fanghei TSAU</td> <td>08/19/2010</td> </tr> <tr> <td>Wen-Chen CHANG</td> <td>08/19/2010</td> </tr> </tbody> </table>		Name	Execution Date	Chi-Chang CHEN	08/19/2010	Huan-Ruei SHIU	08/19/2010	Chun-Hsing WU	08/19/2010	Fanghei TSAU	08/19/2010	Wen-Chen CHANG	08/19/2010
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<table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 20%;"><b>Name:</b></td> <td>INDUSTRIAL TECHNOLOGY RESEARCH INSTITUTE</td> </tr> <tr> <td><b>Street Address:</b></td> <td>No. 195, Sec. 4, Chung Hsing R., Chutung,</td> </tr> <tr> <td><b>City:</b></td> <td>Hsinchu</td> </tr> <tr> <td><b>State/Country:</b></td> <td>TAIWAN</td> </tr> <tr> <td><b>Postal Code:</b></td> <td>31040</td> </tr> </table>		<b>Name:</b>	INDUSTRIAL TECHNOLOGY RESEARCH INSTITUTE	<b>Street Address:</b>	No. 195, Sec. 4, Chung Hsing R., Chutung,	<b>City:</b>	Hsinchu	<b>State/Country:</b>	TAIWAN	<b>Postal Code:</b>	31040		
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<b>CORRESPONDENCE DATA</b>													
<p><b>Fax Number:</b> (202)408-4400</p> <p><i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p><b>Phone:</b> 2024084000</p> <p><b>Email:</b> sopheareak.in@finnegan.com</p> <p><b>Correspondent Name:</b> FINNEGAN HENDERSON</p> <p><b>Address Line 1:</b> 901 NEW YORK AVE., NW</p> <p><b>Address Line 4:</b> WASHINGTON, DISTRICT OF COLUMBIA 20001</p>													
<b>ATTORNEY DOCKET NUMBER:</b>	06720.0316												
<b>NAME OF SUBMITTER:</b>	Sopheareak C. In												

OP \$40.00 12860460

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**PATENT**  
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Total Attachments: 2

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## ASSIGNMENT

WHEREAS, Chi-Chang CHEN, Huan-Ruei SHIU, Chun-Hsing WU, Fanghei TSAU, and Wen-Chen CHANG hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: MODULARIZED FUEL CELL DEVICES AND FLUID FLOW PLATE ASSEMBLIES

Filed: \_\_\_\_\_ Serial No. \_\_\_\_\_  
Executed on: August 19, 2010

WHEREAS, Industrial Technology Research Institute of No. 195, Sec. 4, Chung Hsing Rd., Chutung, Hsinchu 31040, Taiwan, R. O. C. hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Chi-Chang CHEN  
Chi-Chang CHEN

August 19, 2010  
Date:

Huan-Ruei SHIU  
Huan-Ruei SHIU

August 19, 2010  
Date:

# ASSIGNMENT

Chun-Hsing Wu  
Chun-Hsing WU

August 19, 2010  
Date:

Lia  
Fanghei TSAU

August 19, 2010  
Date:

Wen-Chen Chang  
Wen-Chen CHANG

August 19, 2010  
Date: